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INFORMATION DISCLOSURE CITATION IN AN APPLICATION (PTO-1449) APPLICANT Rahul SURANA et al. FILING DATE ATTY. DOCKET NO. 10/809,906 SERIAL NO. 10/809,906

GROUP March 26, 2004 **U.S. PATENT DOCUMENTS EXAMINER'S** FILING INITIALS PATENT NO. DATE NAME **CLASS** SUBCLASS DATE 6,159,075 12/12/00 SLM **Zhang** 10/13/99 6,217,412 B1 04/17/01 Campbell et al. 08/11/99 6,222,936 B1 04/24/01 Phan et al. 09/13/99 2001/0003084 A1 06/07/01 Finarov 12/04/00 6,280,289 B1 08/28/01 Wiswesser et al. 11/02/98 2001/0039462 A1 11/08/01 Mendez et al. 04/02/01 2002/0081951-A1 06/27/02 Boyd et al. 02/20/02 2002/0089676 A1 07/11/02 Pecen et al. 04/26/00 6,435,952 B1 08/20/02 Boyd et al. 06/30/00 2003/0020909 A1 01/30/03 SLU Adams et al. 04/09/01 EXAMINER DATE CONSIDERED

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ATTY, DOCKET NO. INFORMATION DISCLOSURE SERIAL NO. 008089 USA/MTCG/PCTRL 10/809,906 CITATION IN AN APPLICATION (PTO-1449) APPLICANT Rahul SURANA et al. **FILING DATE** GROUP March 26, 2004 **U.S. PATENT DOCUMENTS EXAMINER'S** FILING INITIALS PATENT NO. DATE CLASS NAME **SUBCLASS** DATE 3,205,485 09/07/65 Noltingk 10/21/60 3,229,198 01/11/66 Libby 09/28/62 3,767,900 10/23/73 Chao et al. 06/23/71 3,920,965 11/18/75 Sohrwardy 03/04/74 4,000,458 12/28/76 Miller et al. 08/21/75 4,207,520 06/10/80 Flora et al. 04/06/78 4,209,744 06/24/80 Gerasimov et al. 03/27/78 4,302,721 11/24/81 Urbanek et al. 05/15/79 4,368,510 01/11/83 Anderson 10/20/80 4,609,870 09/02/86 Lale et al. 09/13/84 4,616,308 10/07/86 Morshedi et al. 12/02/85 4,663,703 05/05/87 Axelby et al. 10/02/85 4,698,766 10/06/87 Entwistle et al. 05/17/85 4,750,141 06/07/88 Judell et al. 11/26/85 4,755,753 07/05/88 Chern 07/23/86 4,757,259 07/12/88 Charpentier 11/05/86 4,796,194 01/03/89 Atherton 08/20/86 4,901,218 02/13/90 Cornwell 03/04/88 4,938,600 07/03/90 Into 02/09/89 4,967,381 10/30/90 Lane et al. 07/06/89 5,089,970 02/18/92 Lee et al. 10/05/89 5,108,570 04/28/92 Wang 03/30/90 5,208,765 05/04/93 Turnbull 07/20/90 5,220,517 06/15/93 Sierk et al. 08/31/90 5,226,118 07/06/93 Baker et al. 01/29/91 5,231,585 07/27/93 Kobayashi et al. 06/20/90 5,236,868 08/17/93 Nulman 04/20/90 5,260,868 11/09/93 800 Gupta et al. 10/15/91 **EXAMINER** DATE CONSIDERED 12/12/05

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ATTY. DOCKET NO. INFORMATION DISCLOSURE SERIAL NO. 008089 USA/MTCG/PCTRL 10/809,906 CITATION IN AN **APPLICATION** (PTO-1449) APPLICANT Rahul SURANA et al. FILING DATE **GROUP** March 26, 2004 **U.S. PATENT DOCUMENTS EXAMINER'S** FILING INITIALS PATENT NO. DATE NAME CLASS SUBCLASS DATE 5,546,312 08/13/96 Mozumder et al. SUM 02/24/94 5,553,195 09/03/96 Meijer 09/29/94 5,586,039 12/17/96 Hirsch et al. 02/27/95 5,599,423 02/04/97 Parker et al. 06/30/95 5,602,492 02/11/97 Cresswell et al. 04/28/94 5,603,707 02/18/97 Trombetta et al. 11/28/95 5,617,023 04/01/97 Skalski 02/02/95 5,627,083 05/06/97 Tounai 05/12/95 5,629,216 05/13/97 Wijaranakula et al. 02/27/96 5,642,296 06/24/97 Saxena 07/29/93 07/08/97 5,646,870 Krivokapic et al. 02/13/95 5,649,169 07/15/97 Berezin et al. 06/20/95 5,654,903 08/05/97 Reitman et al. 11/07/95 5,655,951 08/12/97 Meikle et al. 09/29/95 5,657,254 08/12/97 Sierk et al. 04/15/96 5,661,669 08/26/97 Mozumder et al. 06/07/95 5,663,797 09/02/97 Sandhu 05/16/96 5,664,987 09/09/97 Renteln 09/04/96 5,665,199 09/09/97 Sahota et al. 06/23/95 5,666,297 09/09/97 Britt et al. 05/13/94 5,667,424 09/16/97 Pan 09/25/96 5,674,787 10/07/97 Zhao et al. 01/16/96 5,694,325 12/02/97 Fukuda et al. 11/22/95 5,698,989 12/16/97 Nulman 09/13/96 5,719,495 02/17/98 Moslehi 06/05/96 5.719.796 02/17/98 Chen 12/04/95 5,735,055 04/07/98 Hochbein et al. 04/23/96 5,740,429 04/14/98 Wang et al. SLM 07/07/95 **EXAMINER** DATE CONSIDERED 12/12/05

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ATTY. DOCKET NO. INFORMATION DISCLOSURE SERIAL NO. 008089 USA/MTCG/PCTRL 10/809,906 CITATION IN AN **APPLICATION** (PTO-1449) APPLICANT Rahul SURANA et al. FILING DATE GROUP March 26, 2004 **U.S. PATENT DOCUMENTS EXAMINER'S** FILING INITIALS PATENT NO. DATE NAME CLASS SUBCLASS DATE 6.127.263 10/03/00 Parikh 07/10/98 6,128,016 10/03/00 Coelho et al. 12/20/96 6,136,163 10/24/00 Cheung et al. 03/05/99 6,141,660 10/31/00 Bach et al. 07/16/98 6,143,646 11/07/00 Wetzel 06/03/97 6,148,099 11/14/00 Lee et al. 07/03/97 6,148,239 11/14/00 Funk et al. 12/12/97 6,148,246 11/14/00 Kawazome 06/10/98 6,150,664 11/21/00 Su 06/29/99 6,159,644 12/12/00 Satoh et al. 03/06/96 6,161,054 B1 12/12/00 Rosenthal et al. 09/17/98 6,169,931 B1 01/02/01 Runnels 07/29/98 6,172,756 B1 01/09/01 Chalmers et al. 12/11/98 6,173,240 B1 01/09/01 Sepulveda et al. 11/02/98 6,175,777 B1 01/16/01 Kim 01/16/98 6,178,390 B1 01/23/01 Jun 09/08/98 6,183,345 B1 02/06/01 Kamono et al. 03/20/98 6,185,324 B1 02/06/01 Ishihara et al. 01/31/95 6,191,864 BI 02/20/01 Sandhu 02/29/00 6,192,291 B1 02/20/01 Kwon 10/08/98 6,197,604 BI 03/06/01 Miller et al. 10/01/98 6,204,165 B1 03/20/01 Ghoshal 06/24/99 6,210,983 B1 04/03/01 Atchison et al. 06/15/99 6,211,094 B1 04/03/01 Jun et al. 08/23/99 6,214,734 B1 04/10/01 Bothra et al. 11/20/98 6,219,711 B1 04/17/01 Chari 10/01/97 EXAMINER DATE CONSIDERED led over 12/12/08

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ATTY. DOCKET NO. SERIAL NO. INFORMATION DISCLOSURE 008089 USA/MTCG/PCTRL 10/809,906 CITATION IN AN APPLICATION (PTO-1449) APPLICANT Rahul SURANA et al. FILING DATE GROUP March 26, 2004 U.S. PATENT DOCUMENTS **EXAMINER'S** FILING **INITIALS** PATENT NO. DATE NAME **CLASS SUBCLASS** DATE Som 6,226,792 B1 05/01/01 Goiffon et al. 10/14/98 6,230,069 B1 05/08/01 Campbell et al. 06/26/98 6,236,903 B1 05/22/01 Kim et al. 09/25/98 2001/0001755 A1 05/24/01 Sandhu et al. 12/29/00 6,240,330 B1 05/29/01 Kurtzberg et al. 05/28/97 6,240,331 B1 05/29/01 Yun 08/18/98 6,245,581 B1 06/12/01 Bonser et al. 04/19/00 6,246,972 B1 06/12/01 Klimasauskas 05/27/99 6,248,602 B1 06/19/01 Bode et al. 11/01/99 6,249,712 B1 06/19/01 Boiquaye 09/25/96 6,252,412 B1 06/26/01 Talbot et al. 01/08/99 6,253,366 B1 06/26/01 Mutschler, III 03/31/99 6,263,255 B1 07/17/01 Tan et al. 05/18/98 6,271,670 B1 08/07/01 Caffey 02/08/99 6,276,989 B1 08/21/01 Campbell et al. 08/11/99 6,278,899 B1 08/21/01 Piche et al. 10/06/98 6,284,622 B1 09/04/01 Campbell et al. 10/25/99 6,287,879 B1 09/11/01 Gonzales et al. 08/11/99 6,290,572 B1 09/18/01 Hofmann 03/23/00 6,292,708 B1 Allen et al. 09/18/01 06/11/98 6,298,274 B1 10/02/01 Inoue 09/01/99 6,298,470 B1 10/02/01 Breiner et al. 04/15/99 6,303,395 B1 10/16/01 Nulman 06/01/99 6,304,999 B1 10/16/01 Toprac et al. 10/23/00 2001/0030366 A1 10/18/01 Nakano et al. 03/07/01 6,307,628 B1 10/23/01 Lu et al. 08/18/00 6,314,379 B1 11/06/01 Hu et al. 12/04/97 EXAMINER DATE CONSIDERED Uesta 12/12/05

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INFORMATION DISCLOSURE ATTY. DOCKET NO. SERIAL NO. 008089 USA/MTCG/PCTRL 10/809,906 CITATION IN AN APPLICATION (PTO-1449) APPLICANT Rahul SURANA et al. FILING DATE **GROUP** March 26, 2004 U.S. PATENT DOCUMENTS **EXAMINER'S** FILING INITIALS PATENT NO. DATE NAME **CLASS** SUBCLASS DATE 2001/0040997 A1 11/15/01 Suy Tsap et al. 05/15/01 6,320,655 B1 11/20/01 Matsushita et al. 03/15/00 2001/0042690 A1 11/22/01 Talieh 12/14/00 2001/0044667 A1 11/22/01 Nakano et al. 05/16/01 6,324,481 B1 11/27/01 Atchison et al. 06/15/99 6,334,807 B1 01/01/02 Lebel et al. 04/30/99 6,336,841 B1 01/08/02 Chang 03/29/01 6,340,602 B1 01/22/02 Johnson et al. 02/12/01 6,345,288 BI 02/05/02 Reed et al. 05/15/00 6,345,315 B1 02/05/02 Mishra 08/12/98 6,346,426 B1 02/12/02 Toprac et al. 11/17/00 2002/0032499 03/14/02 Wilson et al. 05/04/01 6,360,133 B1 03/19/02 Campbell et al. 06/17/99 03/19/02 6,360,184 B1 Jacquez 03/26/97 6,363,294 B1 03/26/02 Coronel et al. 12/29/98 6,366,934 B1 04/02/02 Cheng et al. 06/02/99 6,368,879 B1 04/09/02 Toprac 09/22/99 6,368,883 B1 04/09/02 Bode et al. 08/10/99 6,368,884 B1 04/09/02 Goodwin et al. 04/13/00 6,379,980 B1 04/30/02 Торгас 07/26/00 6,388,253 B1 05/14/02 11/02/00 6,389,491 BI 05/14/02 Jacobson et al. 03/23/99 2002/0058460 A1 05/16/02 Lee et al. 09/14/01 6,395,152 B1 05/28/02 Wang 07/02/99 6,397,114 B1 05/28/02 Eryurek et al. 05/03/99 6,400,162 B1 06/04/02 Mallory et al. 07/21/00 6,405,096 B1 06/11/02 Toprac et al. 08/10/99 6,405,144 B1 06/11/02 Toprac et al. 01/18/00 **EXAMINER** DATE CONSIDERED Dhe 12/12/05

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INFORMATION DISCLOSURE ATTY. DOCKET NO. SERIAL NO. 008089 USA/MTCG/PCTRL 10/809,906 CITATION IN AN APPLICATION (PTO-1449) APPLICANT Rahul SURANA et al. FILING DATE **GROUP** March 26, 2004 U.S. PATENT DOCUMENTS EXAMINER'S FILING INITIALS PATENT NO. DATE NAME CLASS **SUBCLASS** DATE Suy 2002/0070126 A1 06/13/02 Sato et al. 09/19/01 2002/0077031 A1 06/20/02 Johannson et al. 07/06/01 2002/0102853 A1 08/01/02 Li et al. 12/20/01 2002/0107599 A1 08/08/02 Patel et al. 01/25/01 2002/0107604 A1 08/08/02 Riley et al. 12/06/00 6,438,438 B1 08/20/02 Takagi et al. 01/02/98 2002/0113039 A1 08/22/02 Mok et al. 02/16/01 6,440,295 B1 08/27/02 Wang 02/04/00 6,442,496 B1 08/27/02 Pasadyn et al. 08/08/00 2002/0127950 A1 09/12/02 Hirose et al. 03/08/01 2002/0128805 A1 09/12/02 Goldman et al. 12/26/00 6,455,937 B1 09/24/02 Cunningham 03/17/99 2002/0149359 A1 10/17/02 Crouzen et al. 08/18/01 6,470,230 B1 10/22/02 Toprac et al. 01/04/00 6,479,902 B1 11/12/02 Lopatin et al. 06/29/00 6,479,990 B2 11/12/02 Mednikov et al. 06/18/01 6,482,660 B2 11/19/02 Conchieri et al. 03/19/01 6,486,492 B1 11/26/02 Su 11/20/00 6,492,281 B1 12/10/02 Song et al. 09/22/00 2002/0185658 A1 12/12/02 Inoue et al. 06/14/01 2002/0193902 A1 12/19/02 Shanmugasundram et al. 06/18/02 2002/0197745 A1 12/26/02 Shanmugasundram et al. 08/31/01 2002/0197934 A1 12/26/02 Paik 11/30/01 2002/0199082 A1 34 12/26/02 Shanmugasundram et al. 06/18/02 **EXAMINER** DATE CONSIDERED 12/12/05

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Pad Conditioner Directional Velocity to

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